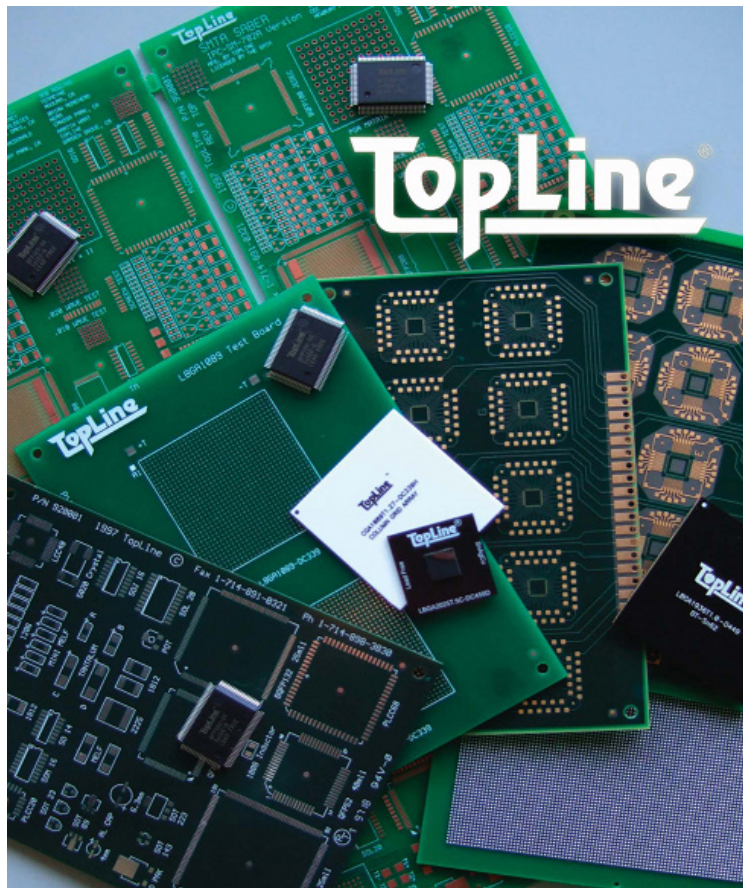




Ball & Bump Kits BGA

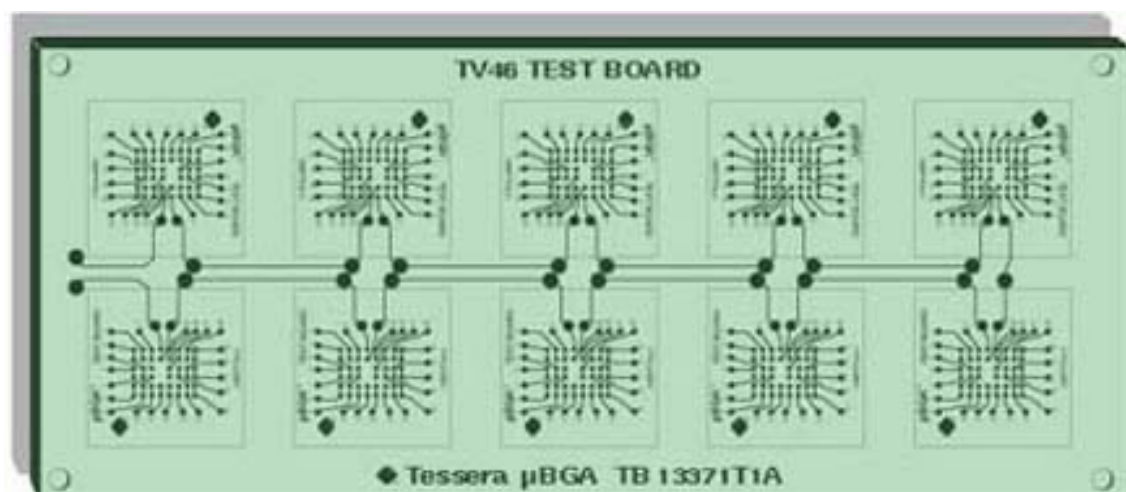




BGA46 0.75 mm Pitch Test Kit

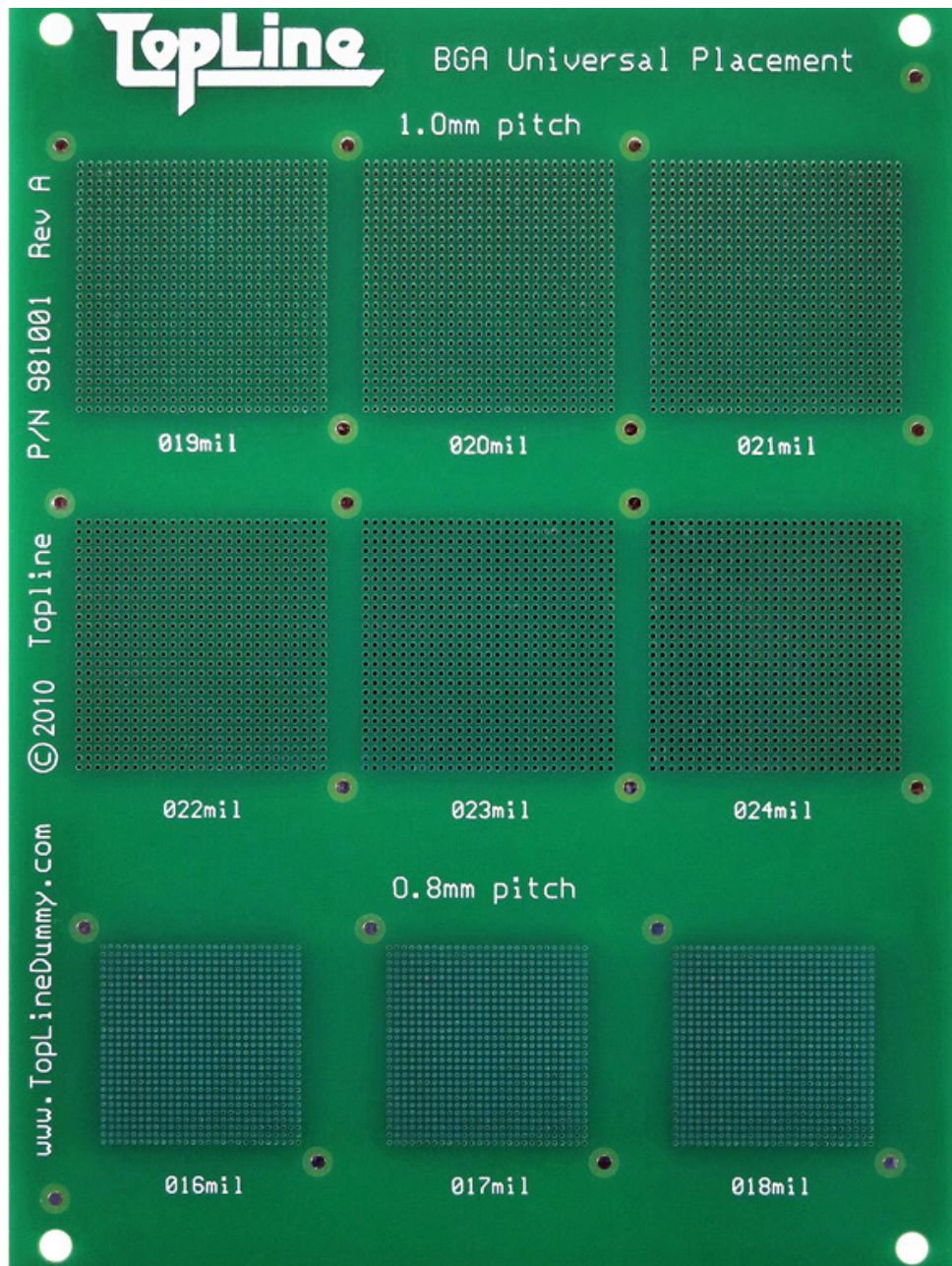
Board Features

- Gold plated (ENIG) Au
- LPI solder mask
- Tetra functional FR4 Board .03" (0.8mm)
- Single sided
- Tooling holes .125"
- Fiducial marks



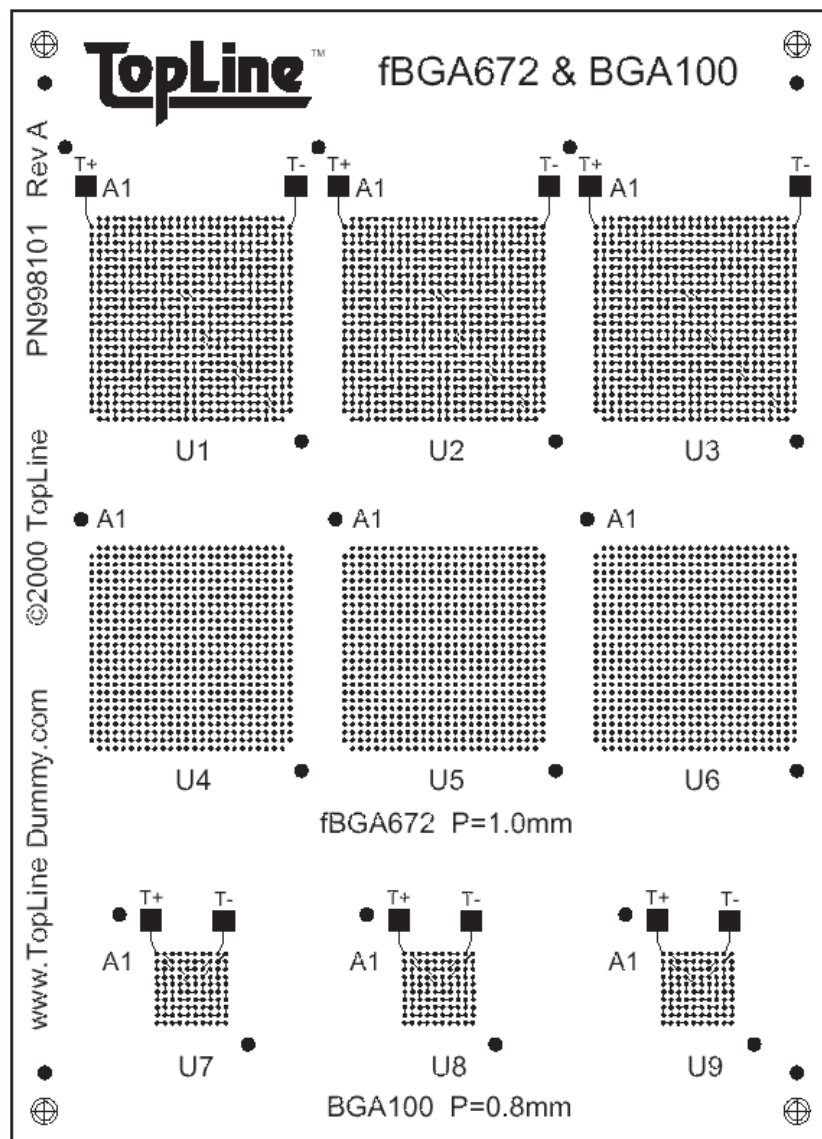


Universal BGA Kit 1.0mm/0.8mm Pitch





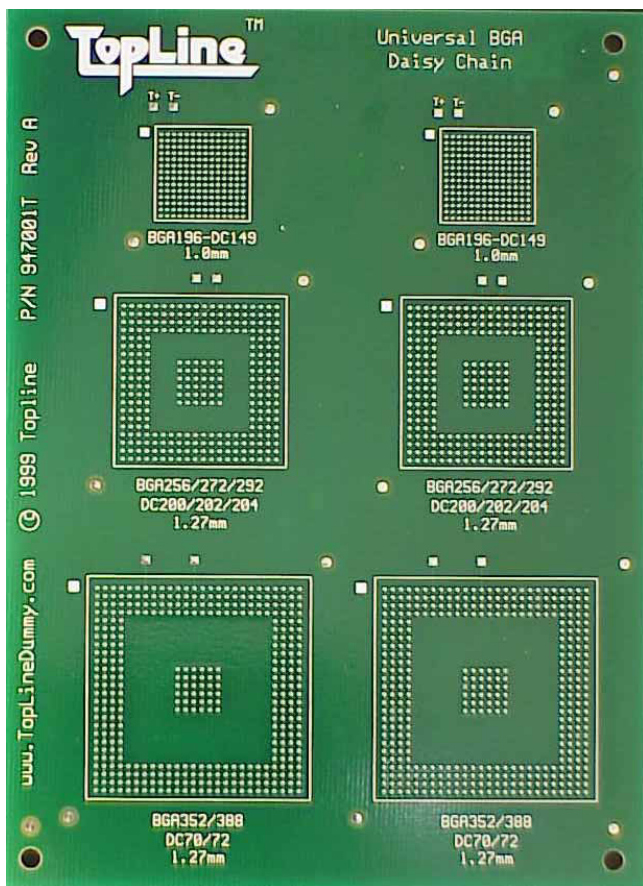
Fine Pitch BGA With Daisy Chain Test 1.0mm/0.8mm Pitch



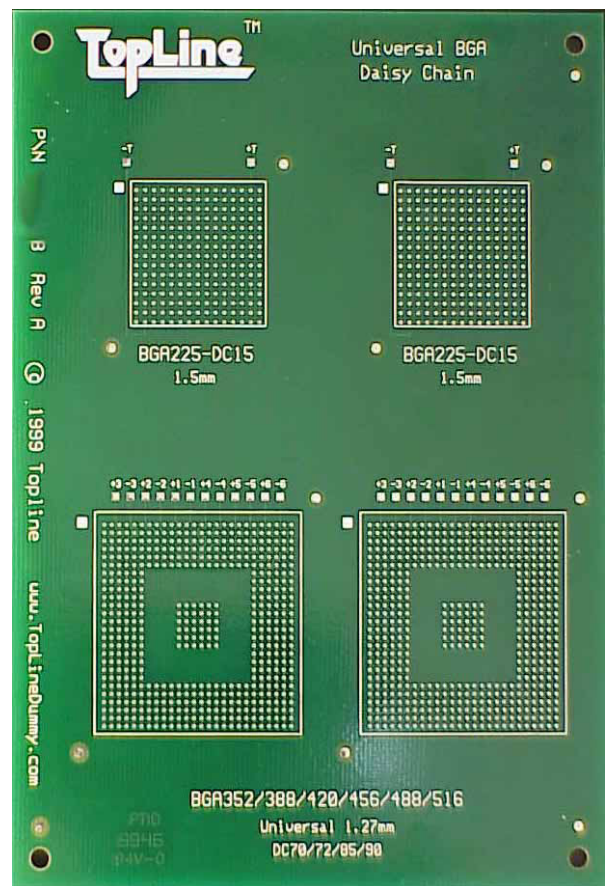


Universal BGA Daisy-Chain Kit 1.0/1.27mm Pitch

Top Bare Board



Bottom Bare Board



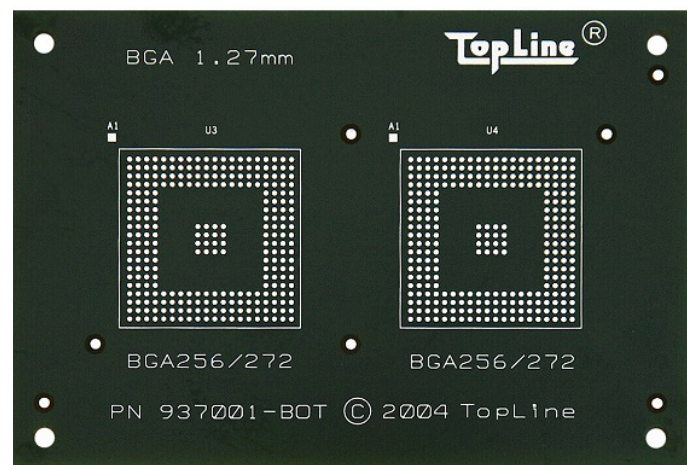


BGA256/BGA272 1.27mm Pitch

Board Features

- Choice of finish:
 - Immersion Tin (Sn)
 - ENIG (Ni/Au)Gold
 - HASL SnPb
- LPI solder mask - PSR4000 AUS5
- FR4 $T_g=170^{\circ}\text{C}$
- Size - 2.75" x 4.0" (7x10cm)
- Thickness 0.062" (1.6mm)
- Lead free RoHS version
- Double sided - patterns repeat on both sides

Top Bare Board



Top After Assembly

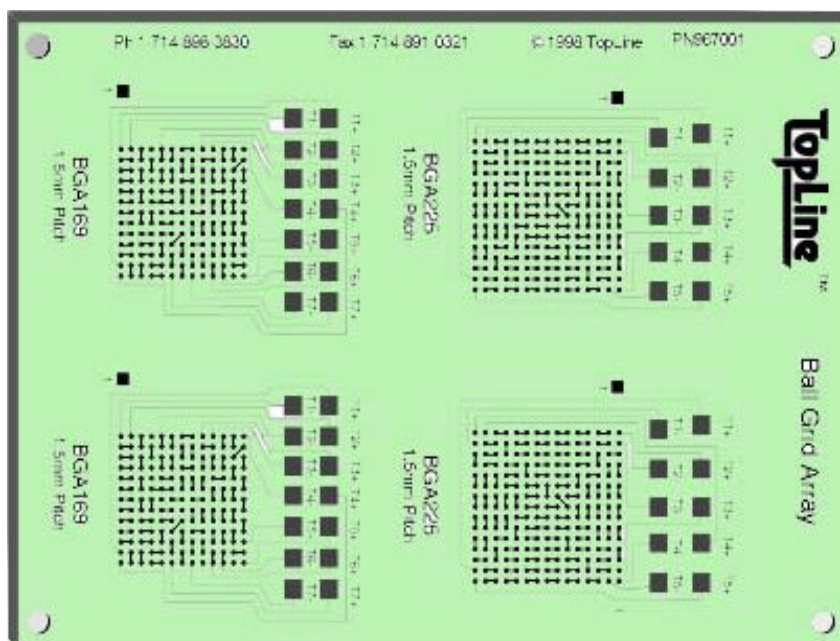




BGA169 & BGA225 With Daisy Chain Test 1.5mm Pitch

Board Features

- Hot Air Soldering Leveling
- LPI Solder Mask
- FR4 Board .062"
- Double Sided
- Tooling Holes .125"
- Fiducial Marks





Universal BGA Kit 1.27mm & 1.5mm Pitch

Board Features

- Choice of finish:
 - Immersion Tin (Sn)
 - ENIG (Ni/Au)Gold
 - OSP Copper
 - Immersion Silver
 - HASL SnPb
- LPI solder mask - PSR4000 AUS5
- FR4 Tg=170°C
- Size - 4"x5.5" (10x14cm)
- Thickness 0.062" (1.6mm)
- Lead free RoHS version
- Tooling Holes .125" (3.17mm)
- IPC Fiducials - 0.62" (1.57mm)
SMEMA 3.1

Top Bare Board

